

2SK3152

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1077-0200

(Previous: ADE-208-732)

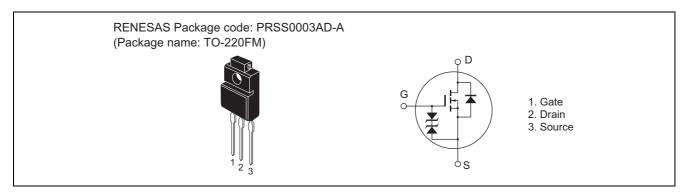
Rev.2.00

Sep 07, 2005

Features

- Low on-resistance $R_{DS} = 100 \text{ m}\Omega$ typ.
- High speed switching
- 4 V gate drive device can be driven from 5 V source

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	120	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	10	A
Drain peak current	I _{D(pulse)} Note1	40	А
Body-drain diode reverse drain current	I _{DR}	10	А
Avalanche current	I _{AP} Note3	10	А
Avalanche energy	E _{AR} Note3	8.5	mJ
Channel dissipation	Pch Note2	25	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	−55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = 25°C

3. Value at Tch = 25°C, Rg \geq 50 Ω

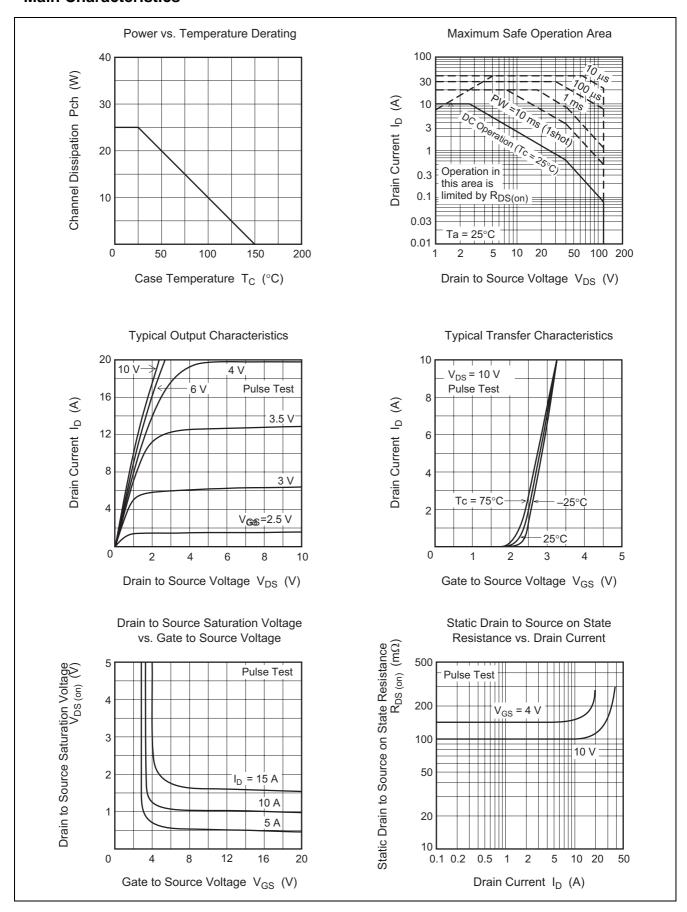
Electrical Characteristics

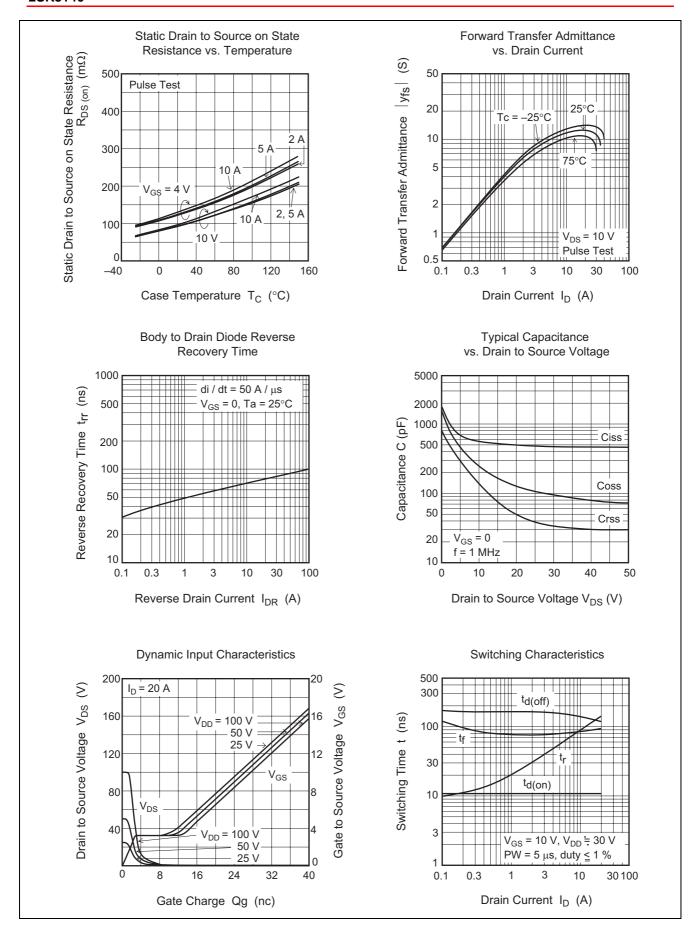
 $(Ta = 25^{\circ}C)$

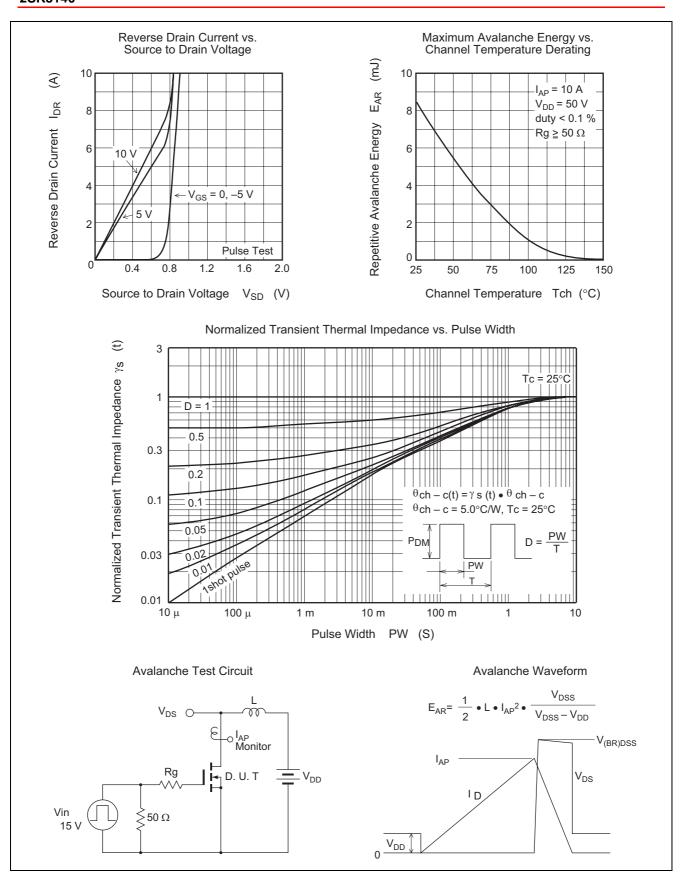
Item	Symbol	Min	Тур	Max	Unit	Test Conditions	
Drain to source breakdown voltage	$V_{(BR)DSS}$	120	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$	
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_		V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$	
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$	
Zero gate voltage drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 120 \text{ V}, V_{GS} = 0$	
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.5	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$	
Static drain to source on state	R _{DS(on)}	_	100	130	mΩ	$I_D = 5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note4}}$	
resistance	R _{DS(on)}	_	130	170	mΩ	$I_D = 5 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note4}}$	
Forward transfer admittance	y _{fs}	5.5	9.5	_	S	$I_D = 5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$	
Input capacitance	Ciss	_	580		pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$	
Output capacitance	Coss	_	240		pF	f = 1 MHz	
Reverse transfer capacitance	Crss	_	130	_	pF		
Turn-on delay time	t _{d(on)}	_	11	_	ns	I _D = 5 A, V _{GS} = 10 V,	
Rise time	t _r	_	55		ns	$R_L = 6 \Omega$	
Turn-off delay time	t _{d(off)}	_	140		ns		
Fall time	t _f	_	80	_	ns		
Body-drain diode forward voltage	V_{DF}	_	0.9	_	V	$I_F = 10 \text{ A}, V_{GS} = 0$	
Body–drain diode reverse recovery time	t _{rr}	_	100	_	V	$I_F = 10 \text{ A}, V_{GS} = 0$ $di_F / dt = 50 \text{ A} / \mu \text{s}$	

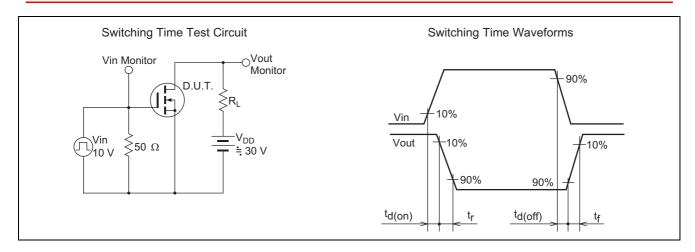
Note: 4. Pulse test

Main Characteristics

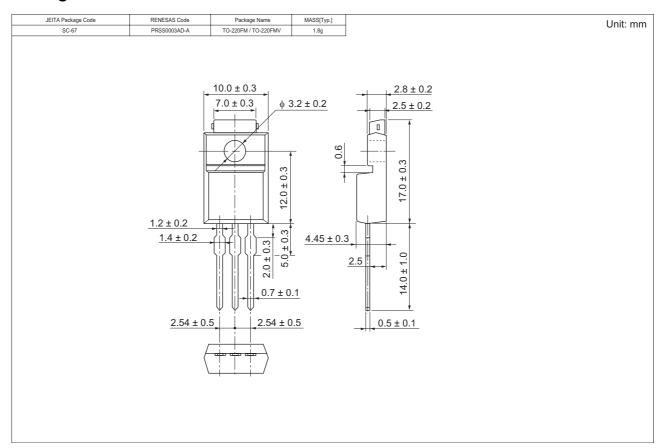








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK3152	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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